ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES International and P	IPC, Bannockt	ourn, Illinois. A	ll rights reserved u ntions.	nder both	This docum level parts, t	ent is a declarat the declaration e	on of the su	bstances all lower	within the manufactur r level materials for w	er listed i hich the r	tem. Note: i nanufacturer	f the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distri				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Info					lfg Informati	on		
Supplier Information													
Company name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
onsemi										2023-06-08			
Contact Name Title - C			itle - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -			itle - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	aester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version	Ν	Manufacturing Site		Weight*	UOM	Unit Type
	MC1404	MC14049UBDR2G LC		LOG CMOS INVERTER HEX		2023-06-08		F	PH1		142.68	mg	Each
Manufacturing Proccess Inform	ation		•					ŀ					
Terminal Plating / Grid Array Material Terminal Base		Cerminal Base	Alloy J	J-STD-020 MSL	Rating	Peak Proc	ess Body Te	emperatur	e Max Time at Peak	Tempera	ture Numb	er of Reflow Cyd	les
Matte Tin (Sn) - annealed CU Alloy			1	1		260		С	30	secor	nds 3		
Comments													
level 1 - maximum time at peak tempera	ture during so	Idering is 10-3	0 seconds										
For more information regarding materia	al composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl httalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg		Epoxy resin	proprietary data		0.1212	mg
			Supplier	Silver (Ag)	7440-22-4		4.0982	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1212	mg
			Supplier	Inorganic filler	Proprietary Data		0.1212	mg
			Supplier	Dicyandiamine	461-58-5		0.0242	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3637	mg
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy resin	proprietary data		2.7555	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7555	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.1022	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2756	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.2213	mg
lating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	0.34	mg	Supplier	Copper (Cu)	7440-50-8		0.34	mg